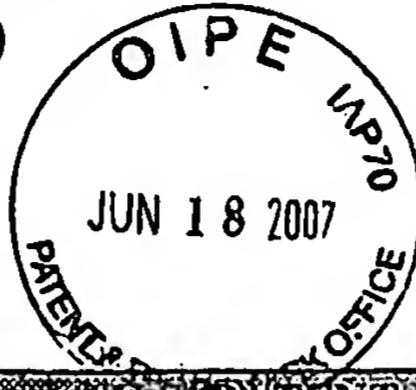


INFORMATION DISCLOSURE
CITATION IN AN
APPLICATION
(PTO-1449)

ATTY. DOCKET NO.
007734 FPS/MMCS/APC

SERIAL NO.
10/665,165



APPLICANT
Joseph Young J. PAIK

FILING DATE
September 18, 2003

GROUP

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APPLICANT
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APPLICANT Joseph Young J. PAIK			
FILING DATE September 18, 2003		GROUP	
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EXAMINER <i>Maet</i>	DATE CONSIDERED 1/21/08		

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U.S. PATENT DOCUMENTS						
EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
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<i>AM</i>	5,740,429	04/14/98	Wang et al.				07/07/95
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	5,910,846	06/08/99	Sandhu			08/19/97
EXAMINER	DATE CONSIDERED			1/21/2008		

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INFORMATION DISCLOSURE
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ATTY. DOCKET NO.
007734 FPS/MMCS/APCSERIAL NO.
10/665,165APPLICANT
Joseph Young J. PAIKFILING DATE
September 18, 2003

GROUP

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EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
	5,912,678	06/15/99	Saxena et al.			04/14/97
	5,916,016	06/29/99	Bothra			10/23/97
	5,923,553	07/13/99	Yi			10/05/96
	5,926,690	07/20/99	Toprac et al.			05/28/97
	5,930,138	07/27/99	Lin et al.			09/10/97
	5,940,300	08/17/99	Ozaki			05/08/97
	5,943,237	08/24/99	Van Boxem			10/17/97
	5,960,185	09/28/99	Nguyen			06/24/96
	5,960,214	09/28/99	Sharpe, Jr. et al.			12/04/96
	5,961,369	10/05/99	Bartels et al.			06/04/98
	5,963,881	10/05/99	Kahn et al.			10/20/97
	5,978,751	11/02/99	Pence et al.			02/25/97
	5,982,920	11/09/99	Tobin, Jr. et al.			01/08/97
	6,002,989	12/14/99	Shiba et al.			04/01/97
	6,017,771	01/25/00	Yang et al.			04/27/98
	6,036,349	03/14/00	Gombar			07/26/96
	6,041,263	03/21/00	Boston et al.			10/01/97
	6,041,270	03/21/00	Steffan et al.			12/05/97
	6,054,379	04/25/00	Yau et al.			02/11/98
	6,064,759	05/16/00	Buckley et al.			11/06/97
	6,072,313	06/06/00	Li et al.			06/17/97
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	6,077,412	06/20/00	Ting et al.			10/30/98
	6,078,845	06/20/00	Friedman			11/25/96
	6,094,688	07/25/00	Mellen-Garnett et al.			03/12/98
	6,097,887	08/01/00	Hardikar et al.			10/27/97
	6,108,092	08/22/00	Sandhu			06/08/99
	6,111,634	08/29/00	Pecen et al.			05/28/97
	6,112,130	08/29/00	Fukuda et al.			10/01/97

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INFORMATION DISCLOSURE CITATION IN AN APPLICATION (PTO-1449)		ATTY. DOCKET NO. 007734 FPS/MMCS/APC		SERIAL NO. 10/665,165		
		APPLICANT Joseph Young J. PAIK				
		FILING DATE September 18, 2003		GROUP		
U.S. PATENT DOCUMENTS						
EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
	6,127,263	10/03/00	Parikh			07/10/98
	6,128,016	10/03/00	Coelho et al.			12/20/96
	6,136,163	10/24/00	Cheung et al.			03/05/99
	6,141,660	10/31/00	Bach et al.			07/16/98
	6,143,646	11/07/00	Wetzel			06/03/97
	6,148,099	11/14/00	Lee et al.			07/03/97
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	6,150,664	11/21/00	Su			06/29/99
	6,159,075	12/12/00	Zhang			10/13/99
	6,159,644	12/12/00	Satoh et al.			03/06/96
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EXAMINER <i>hwall</i>			DATE CONSIDERED <i>1/21/2009</i>			

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	6,314,379 B1	11/06/01	Hu et al.			12/04/97

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EXAMINER'S INITIALS	PATENT APP. NO.	FILING DATE	NAME	TITLE	CLASS	SUB-CLASS
	09/363,966	07/29/99	Arackaparambil et al.	Computer Integrated Manufacturing Techniques		
	09/469,227	12/22/99	Somekh et al.	Multi-Tool Control System, Method and Medium		
	09/619,044	07/19/00	Yuan	System and Method of Exporting or Importing Object Data in a Manufacturing Execution System		
	09/637,620	08/11/00	Chi et al.	Generic Interface Builder		
	09/656,031	09/06/00	Chi et al.	Dispatching Component for Associating Manufacturing Facility Service Requestors with Service Providers		
	09/655,542	09/06/00	Yuan	System, Method and Medium for Defining Palettes to Transform an Application Program Interface for a Service		
	09/725,908	11/30/00	Chi et al.	Dynamic Subject Information Generation in Message Services of Distributed Object Systems		
	09/800,980	03/08/01	Hawkins et al.	Dynamic and Extensible Task Guide		
	09/811,667	03/20/01	Yuan et al.	Fault Tolerant and Automated Computer Software Workflow		
	09/927,444	08/13/01	Ward et al.	Dynamic Control of Wafer Processing Paths in Semiconductor Manufacturing Processes		
	09/928,473	08/14/01	Koh	Tool Services Layer for Providing Tool Service Functions in Conjunction with Tool Functions		
	09/928,474	08/14/01	Krishnamurthy et al.	Experiment Management System, Method and Medium		
	09/943,383	08/31/01	Shanmugasundram et al.	In Situ Sensor Based Control of Semiconductor Processing Procedure		
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	09/998,384	11/30/01	Paik	Feedforward and Feedback Control for Conditioning of Chemical Mechanical Polishing Pad		
EXAMINER <i>hpaik</i>				DATE CONSIDERED <i>1/21/08</i>		

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EXAMINER'S INITIALS	PATENT APP. NO.	FILING DATE	NAME	TITLE	CLASS	SUB-CLASS
	10/084,092	02/28/02	Arackaparambil et al.	Computer Integrated Manufacturing Techniques		
	10/100,184	03/19/02	Al-Bayati et al.	Method, System and Medium for Controlling Semiconductor Wafer Processes Using Critical Dimension Measurements		
	10/135,405	05/01/02	Reiss et al.	Integration of Fault Detection with Run-to-Run Control		
	10/135,451	05/01/02	Shanmugasundram et al.	Dynamic Metrology Schemes and Sampling Schemes for Advanced Process Control in Semiconductor Processing		
	10/172,977	06/18/02	Shanmugasundram et al.	Method, System and Medium for Process Control for the Matching of Tools, Chambers and/or Other Semiconductor-Related Entities		
	10/173,108	06/18/02	Shanmugasundram et al.	Integrating Tool, Module, and Fab Level Control		
	10/174,370	06/18/02	Shanmugasundram et al.	Feedback Control of Plasma-Enhanced Chemical Vapor Deposition Processes		
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	10/377,654	03/04/03	Kokotov et al.	Method, System and Medium for Controlling Manufacturing Process Using Adaptive Models Based on Empirical Data		
	10/393,531	03/21/03	Shanmugasundram et al.	Copper Wiring Module Control		
	10/632,107	08/01/03	Schwarm et al.	Method, System, and Medium for Handling Misrepresentative Metrology Data Within an Advanced Process Control System		
EXAMINER <i>brad</i>				DATE CONSIDERED <i>1/21/08</i>		

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FOREIGN PATENT DOCUMENTS

EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
	61-66104	04/04/86	Japan			X	
	61-171147	08/01/86	Japan			X	
	01-283934	11/15/89	Japan			X	
	0 397 924 A1	11/22/90	Europe			X	
	2,050,247	08/29/91	Canada			X	
	2,165,847	08/29/91	Canada			X	
	2,194,855	08/29/91	Canada			X	
	3-202710	09/04/91	Japan			X	
	05-151231	06/18/93	Japan			X	
	05-216896	08/27/93	Japan			X	
	05-266029	10/15/93	Japan			X	
	06-110894	04/22/94	Japan			X	
	06-176994	06/24/94	Japan			X	
	06-184434	07/05/94	Japan			X	
	06-252236	09/09/94	Japan			X	
	06-260380	09/16/94	Japan			X	
	EP 0 621 522 A2	10/26/94	Europe			X	
	WO 95/34866	12/21/95	WO			X	
	8-23166	01/23/96	Japan			X	
	08-50161	02/20/96	Japan			X	
	08-149583	06/07/96	Japan			X	
	08-304023	11/22/96	Japan			X	
	EP 0 747 795 A2	12/11/96	Europe			X	
	09-34535	02/07/97	Japan			X	
	9-246547	09/19/97	Japan			X	
	WO 98/05066	02/05/98	WO			X	
	10-34522	02/10/98	Japan			X	
	10-173029	06/26/98	Japan			X	

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						Yes	No
	EP 0 869 652 A2	10/07/98	Europe			X	
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	EP 0 877 308 A2	11/11/98	Europe			X	
	EP 0 881 040 A2	12/02/98	Europe			X	
	EP 0 895 145 A1	02/03/99	Europe			X	
	WO 99/09371	02/25/99	WO			X	
	11-67853	03/09/99	Japan			X	
	EP 0 910 123 A1	04/21/99	Europe			X	
	11-126816	05/11/99	Japan			X	
	11-135601	05/21/99	Japan			X	
	WO 99/25520	05/27/99	WO			X	
	EP 0 932 194 A1	07/28/99	Europe			X	
	WO 99/59200	11/18/99	WO			X	
	WO 00/00874	01/06/00	WO			X	
	WO 00/05759	02/03/00	WO			X	
	WO 00/35063	06/15/00	WO			X	
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	WO 00/54325	09/14/00	WO			X	
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	WO 00/79355 A1	12/28/00	WO			X	
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	WO 01/11679 A1	02/15/01	WO			X	
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						Yes	No
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Joseph Young J. PAIK

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